Low Noise Dual/Quad Operational Amplifiers

The MC33078/9 series is a family of high quality monolithic amplifiers employing Bipolar technology with innovative high performance concepts for quality audio and data signal processing applications. This family incorporates the use of high frequency PNP input transistors to produce amplifiers exhibiting low input voltage noise with high gain bandwidth product and slew rate. The all NPN output stage exhibits no deadband crossover distortion, large output voltage swing, excellent phase and gain margins, low open loop high frequency output impedance and symmetrical source and sink AC frequency performance.

The MC33078/9 family offers both dual and quad amplifier versions and is available in the plastic DIP and SOIC packages (P and D suffixes).

Features

- Dual Supply Operation: $\pm 5.0 \text{ V}$ to $\pm 18 \text{ V}$
- Low Voltage Noise: $4.5 \text{ nV}/\sqrt{\text{Hz}}$
- Low Input Offset Voltage: 0.15 mV
- Low T.C. of Input Offset Voltage: 2.0 μV/°C
- Low Total Harmonic Distortion: 0.002%
- High Gain Bandwidth Product: 16 MHz
- High Slew Rate: 7.0 V/μs
- High Open Loop AC Gain: 800 @ 20 kHz
- Excellent Frequency Stability
- Large Output Voltage Swing: +14.1 V/ -14.6 V
- ESD Diodes Provided on the Inputs
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

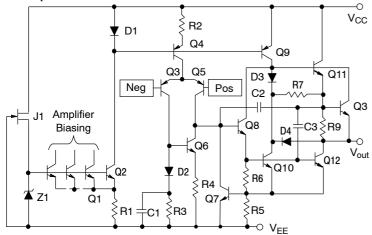


Figure 1. Representative Schematic Diagram (Each Amplifier)



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MARKING DIAGRAMS

DUAL



PDIP-8 P SUFFIX CASE 626





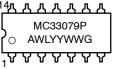
SOIC-8 D SUFFIX CASE 751



QUAD

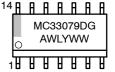


PDIP-14 P SUFFIX CASE 646





SOIC-14 D SUFFIX CASE 751A



A = Assembly Location

WL, L = Wafer Lot YY, Y = Year

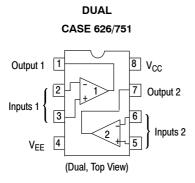
WW, W = Work Week

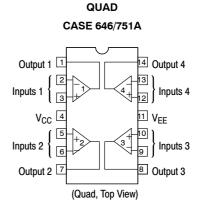
G or ■ = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

PIN CONNECTIONS





MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Supply Voltage (V _{CC} to V _{EE)}	Vs	+36	V	
Input Differential Voltage Range		V _{IDR}	Note 1	V
Input Voltage Range		V _{IR}	Note 1	V
Output Short Circuit Duration (Note 2)	t _{SC}	Indefinite	sec	
Maximum Junction Temperature		TJ	+150	°C
Storage Temperature		T _{stg}	-60 to +150	°C
ESD Protection at any Pin MC33078/NCV33078 MC33079/NCV33079	 Human Body Model Machine Model Human Body Model Machine Model 	V _{esd}	600 200 550 150	V
Maximum Power Dissipation		P _D	Note 2	mW
Operating Temperature Range		T _A	-40 to +85	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Either or both input voltages must not exceed the magnitude of V_{CC} or V_{EE}.

- 2. Power dissipation must be considered to ensure maximum junction temperature (T_J) is not exceeded (see Figure 2).

DC ELECTRICAL CHARACTERISTICS (V_{CC} = +15 V, V_{EE} = -15 V, T_A = 25°C, unless otherwise noted.)

Characteristics	Symbol	Min	Тур	Max	Unit
Input Offset Voltage (R _S = 10 Ω , V _{CM} = 0 V, V _O = 0 V) (MC33078) T _A = +25°C T _A = -40° to +85°C (MC33079) T _A = +25°C T _A = -40° to +85°C	V _{IO}	- - - -	0.15 - 0.15 -	2.0 3.0 2.5 3.5	mV
Average Temperature Coefficient of Input Offset Voltage $R_S = 10 \Omega$, $V_{CM} = 0 V$, $V_O = 0 V$, $T_A = T_{low}$ to T_{high}	$\Delta V_{IO}/\Delta T$	_	2.0	_	μV/°C
Input Bias Current ($V_{CM} = 0$ V, $V_{O} = 0$ V) $T_{A} = +25^{\circ}C$ $T_{A} = -40^{\circ} \text{ to } +85^{\circ}C$	I _{IB}	_ _	300 -	750 800	nA
Input Offset Current ($V_{CM} = 0 \text{ V}, V_O = 0 \text{ V}$) $T_A = +25^{\circ}C$ $T_A = -40^{\circ} \text{ to } +85^{\circ}C$	I _{IO}	- -	25 -	150 175	nA
Common Mode Input Voltage Range ($\Delta V_{IO} = 5.0 \text{ mV}, V_O = 0 \text{ V}$)	V _{ICR}	±13	±14	-	V
Large Signal Voltage Gain (V $_{O}$ = \pm 10 V, R $_{L}$ = 2.0 k Ω) T_{A} = +25°C T_{A} = -40° to +85°C	AvoL	90 85	110 -	- -	dB
Output Voltage Swing ($V_{ID}=\pm 1.0V$) $R_L=600~\Omega$ $R_L=600~\Omega$ $R_L=2.0~k\Omega$ $R_L=2.0~k\Omega$ $R_L=10~k\Omega$ $R_L=10~k\Omega$	V _O + V _O - V _O + V _O - V _O + V _O -	- +13.2 - +13.5	+10.7 -11.9 +13.8 -13.7 +14.1 -14.6	- - - -13.2 - -14	٧
Common Mode Rejection (V _{in} = ±13V)	CMR	80	100	_	dB
Power Supply Rejection (Note 3) $V_{CC}/V_{EE} = +15 \text{ V/} -15 \text{ V to } +5.0 \text{ V/} -5.0 \text{ V}$	PSR	80	105	_	dB
Output Short Circuit Current (V _{ID} = 1.0 V, Output to Ground) Source Sink	l _{sc}	+15 -20	+29 -37	- -	mA
Power Supply Current (V_O = 0 V, All Amplifiers) (MC33078) T_A = +25°C T_A = -40° to +85°C (MC33079) T_A = +25°C T_A = -40° to +85°C	I _D	- - -	4.1 - 8.4 -	5.0 5.5 10 11	mA

^{3.} Measured with V_{CC} and V_{EE} differentially varied simultaneously.

AC ELECTRICAL CHARACTERISTICS ($V_{CC} = +15 \text{ V}$, $V_{EE} = -15 \text{ V}$, $T_A = 25^{\circ}\text{C}$, unless otherwise noted.)

Characteristics	Symbol	Min	Тур	Max	Unit
Slew Rate (V _{in} = –10 V to +10 V, R _L = 2.0 k Ω , C _L = 100 pF A _V = +1.0)	SR	5.0	7.0	-	V/μs
Gain Bandwidth Product (f = 100 kHz)	GBW	10	16	-	MHz
Unity Gain Bandwidth (Open Loop)	BW	-	9.0	-	MHz
Gain Margin (R_L = 2.0 k Ω) C_L = 0 pF C_L = 100 pF	A _m	- -	-11 -6.0	- -	dB
Phase Margin (R _L = 2.0 k Ω) C _L = 0 pF C _L = 100 pF	Фт	- -	55 40	- -	Deg
Channel Separation (f = 20 Hz to 20 kHz)	CS	-	-120	-	dB
Power Bandwidth ($V_O = 27 V_{pp}$, $R_L = 2.0 k\Omega$, THD $\pm 1.0\%$)	BW _p	_	120	-	kHz
Total Harmonic Distortion (R _L = 2.0 k Ω , f = 20 Hz to 20 kHz, V _O = 3.0 V _{rms} , A _V = +1.0)	THD	-	0.002	-	%
Open Loop Output Impedance (V _O = 0 V, f = 9.0 MHz)	Z _O	_	37	-	Ω
Differential Input Resistance (V _{CM = 0 V)}	R _{in}	_	175	-	kΩ
Differential Input Capacitance (V _{CM = 0 V)}	C _{in}	-	12	_	pF
Equivalent Input Noise Voltage ($R_S = 100 \Omega$, $f = 1.0 \text{ kHz}$)	e _n	-	4.5	-	nV/√Hz
Equivalent Input Noise Current (f = 1.0 kHz)	i _n		0.5		Hz√pA/

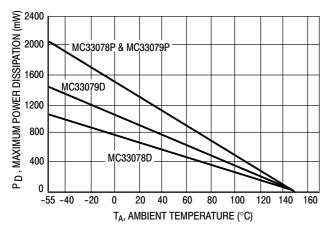


Figure 2. Maximum Power Dissipation versus Temperature

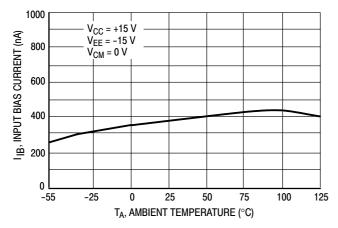


Figure 4. Input Bias Current versus Temperature

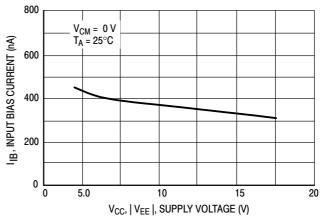


Figure 3. Input Bias Current versus Supply Voltage

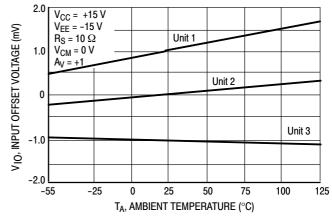


Figure 5. Input Offset Voltage versus Temperature

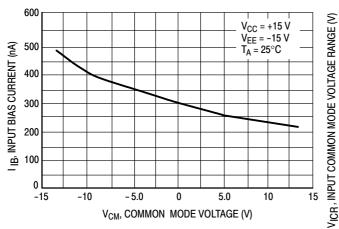


Figure 6. Input Bias Current versus Common Mode Voltage

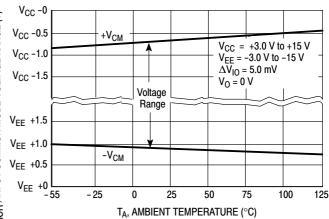


Figure 7. Input Common Mode Voltage Range versus Temperature

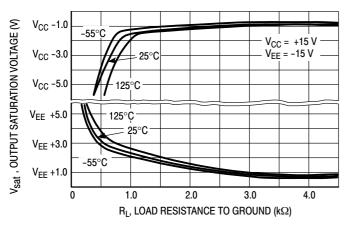


Figure 8. Output Saturation Voltage versus Load Resistance to Ground

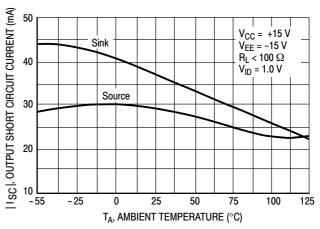


Figure 9. Output Short Circuit Current versus Temperature

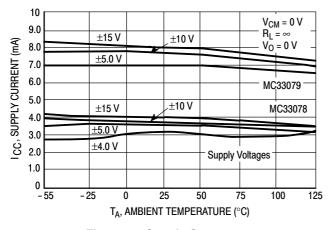


Figure 10. Supply Current versus Temperature

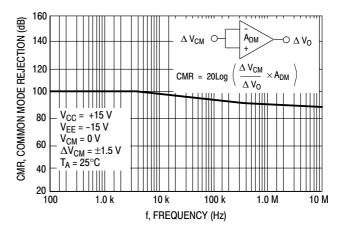


Figure 11. Common Mode Rejection versus Frequency

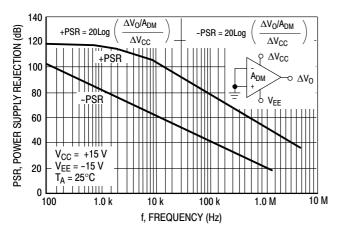


Figure 12. Power Supply Rejection versus Frequency

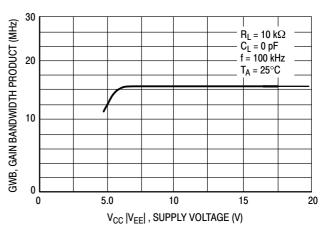


Figure 13. Gain Bandwidth Product versus Supply Voltage

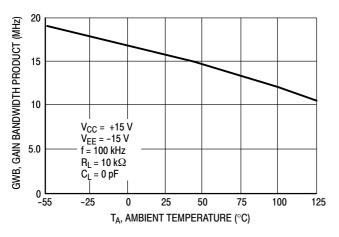


Figure 14. Gain Bandwidth Product versus Temperature

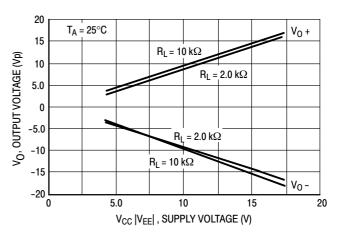


Figure 15. Maximum Output Voltage versus Supply Voltage

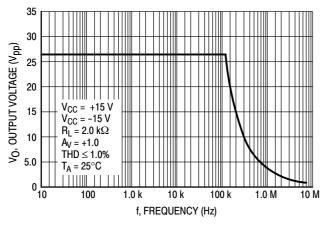


Figure 16. Output Voltage versus Frequency

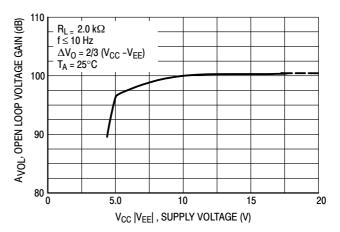


Figure 17. Open Loop Voltage Gain versus Supply Voltage

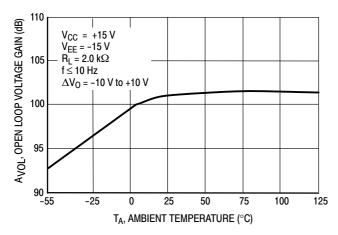


Figure 18. Open Loop Voltage Gain versus Temperature

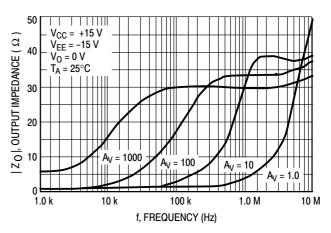


Figure 19. Output Impedance versus Frequency

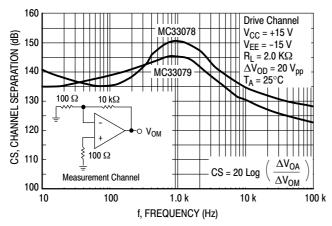


Figure 20. Channel Separation versus Frequency

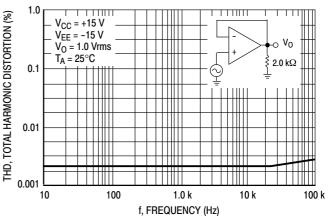


Figure 21. Total Harmonic Distortion versus Frequency

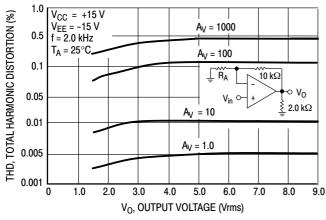


Figure 22. Total Harmonic Distortion versus Output Voltage

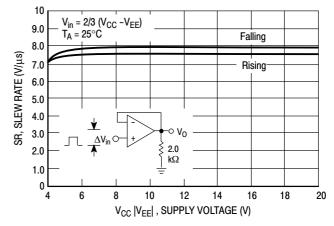


Figure 23. Slew Rate versus Supply Voltage

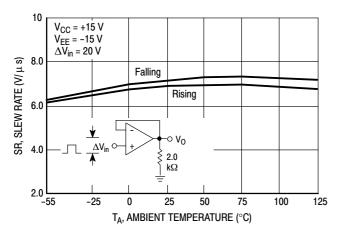


Figure 24. Slew Rate versus Temperature

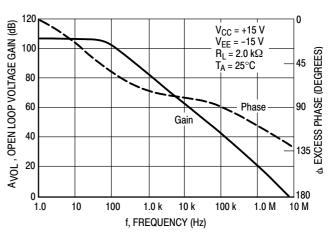


Figure 25. Voltage Gain and Phase versus Frequency

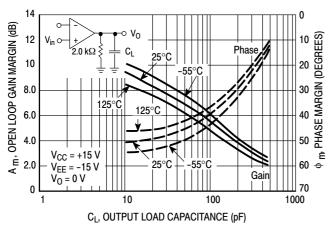


Figure 26. Open Loop Gain Margin and Phase Margin versus Load Capacitance

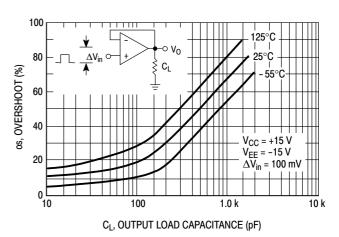


Figure 27. Overshoot versus Output Load Capacitance

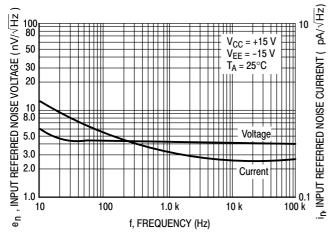


Figure 28. Input Referred Noise Voltage and Current versus Frequency

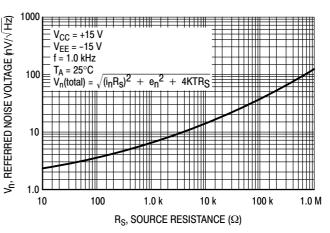


Figure 29. Total Input Referred Noise Voltage versus Source Resistance

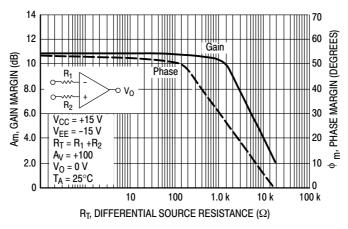


Figure 30. Phase Margin and Gain Margin versus Differential Source Resistance

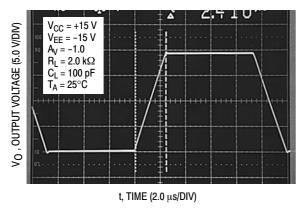


Figure 31. Inverting Amplifier Slew Rate

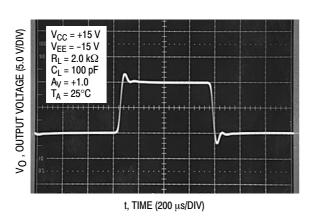


Figure 33. Non-inverting Amplifier Overshoot

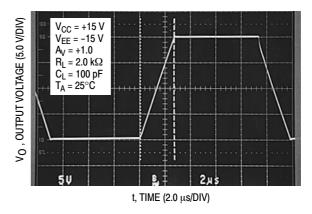


Figure 32. Non-inverting Amplifier Slew Rate

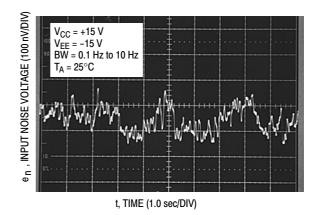
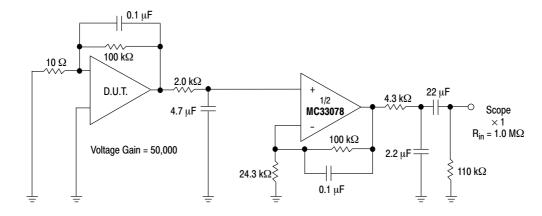


Figure 34. Low Frequency Noise Voltage versus Time



Note: All capacitors are non-polarized.

Figure 35. Voltage Noise Test Circuit (0.1 Hz to 10 Hz_{p-p})

ORDERING INFORMATION

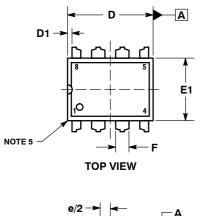
Device	Package	Shipping [†]
MC33078DG		98 Units / Rail
MC33078DR2G	SOIC-8 (Pb-Free)	0500 / Tono 9 Dool
NCV33078DR2G*	, ,	2500 / Tape & Reel
MC33078P	PDIP-8	
MC33078PG	PDIP-8 (Pb-Free)	50 Units / Rail
MC33079DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC33079DR2G	SOIC-14	2500 / Tape & Reel
NCV33079DR2G*	(Pb-Free)	2500 / Tape & Neel
MC33079P	PDIP-14	
MC33079PG	PDIP-14 (Pb-Free)	25 Units / Rail

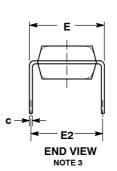
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

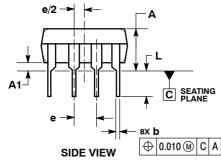
^{*}NCV devices are qualified for automotive use.

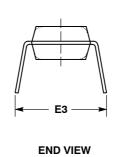
PACKAGE DIMENSIONS

PDIP-8 **N SUFFIX** CASE 626-05 ISSUE M









- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: INCHES.

 3. DIMENSION E IS MEASURED WITH THE LEADS RESTRAINED PARALLEL AT WIDTH E2.

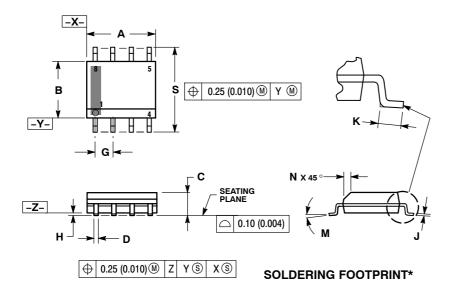
 4. DIMENSION E 1 DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INCHES			MILLIMETERS			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α			0.210			5.33	
A1	0.015			0.38			
b	0.014	0.018	0.022	0.35	0.46	0.56	
С	0.008	0.010	0.014	0.20	0.25	0.36	
D	0.355	0.365	0.400	9.02	9.27	10.02	
D1	0.005			0.13			
E	0.300	0.310	0.325	7.62	7.87	8.26	
E1	0.240	0.250	0.280	6.10	6.35	7.11	
E2	(0.300 BSC			7.62 BSC		
E3			0.430			10.92	
е	(0.100 BS	С		2.54 BSC	;	
L	0.115	0.130	0.150	2.92	3.30	3.81	

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AK**

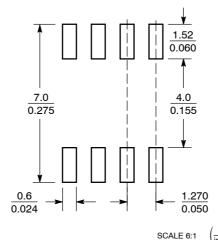


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- PEH SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
- MAXIMUM MATERIAL CONDITION. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751-07.

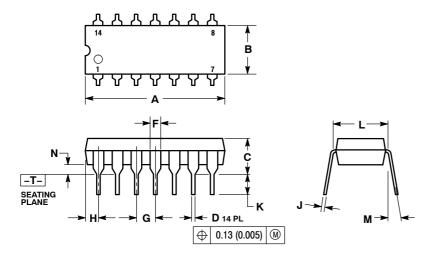
	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
Κ	0.40	1.27	0.016	0.050	
М	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0 244	



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

PDIP-14 CASE 646-06 **ISSUE P**

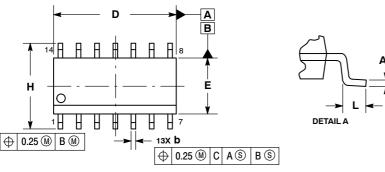


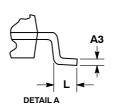
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

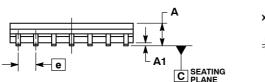
	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	19.56	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100	BSC	2.54 BSC		
Н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.290	0.310	7.37	7.87	
M		10 °		10 °	
N	0.015	0.039	0.38	1.01	

PACKAGE DIMENSIONS

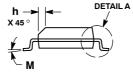
SOIC-14 NB CASE 751A-03 **ISSUE K**







14X 0.58

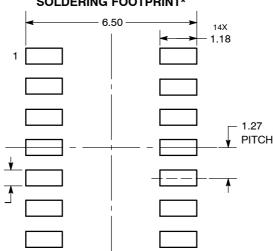


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- ASME 114.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
АЗ	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27 BSC		0.050 BSC	
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
М	0 °	7 °	0 °	7°

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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